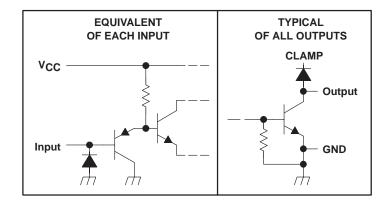
- Characterized for Use to 300 mA
- No Output Latch-Up at 55 V (After Conducting 300 mA)
- High-Voltage Outputs (100 V Typ)
- Output Clamp Diodes for Transient Suppression (300 mA, 70 V)
- TTL- or MOS-Compatible Diode-Clamped Inputs
- pnp Transistor Inputs Reduce Input Current
- Standard Supply Voltage
- Suitable for Hammer-Driver Applications
- Plastic DIP (P) With Copper-Lead Frame Provides Cooler Operation and Improved Reliability

# description

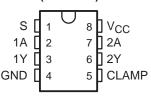
The SN75476 through SN75478 are dual peripheral drivers designed for use in systems that require high current, high voltage, and fast switching times. The SN75476, SN75477, and SN75478 provide AND, NAND, and OR drivers respectively. These devices have diode-clamped inputs as well as high-current, high-voltage clamp diodes on the outputs for inductive transient protection.

The SN75476, SN75477, and SN75478 drivers are characterized for operation from 0°C to 70°C.

#### schematics of inputs and outputs



# D OR P PACKAGE (TOP VIEW)



### Function Tables SN75476

SN75476 (each AND driver)

INPU	OUTPUT				
Α	A S				
Н	Н	Н			
L	Χ	L			
X	L	L			

#### SN75477 (each NAND driver)

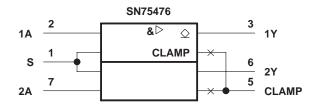
INPU	OUTPUT				
Α	A S				
Н	Н	L			
L	X	Н			
X	L	Н			

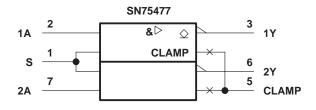
# SN75478 (each OR driver)

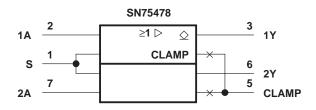
INPU	OUTPUT	
Α	S	Υ
Н	Х	Н
Х	Н	Н
L	L	L

H = high level, L = low level X = irrelevant

## logic symbols†

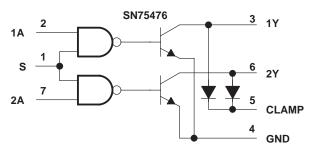




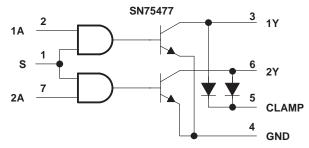


<sup>†</sup> These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC publication 617-12.

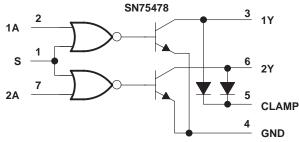
# logic diagrams (positive logic)



Positive Logic: Y = AS or  $\overline{A} + \overline{S}$ 



Positive Logic:  $Y = \overline{AS}$  or  $\overline{A} + \overline{S}$ 



Positive Logic: Y = A+S or  $\overline{A} \overline{S}$ 

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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V <sub>CC</sub> (see Note 1)	7 V
Input voltage, V <sub>I</sub>	5.5 V
Continuous output current (see Note 2)	400 mA
Peak output current: $t_W \le 10$ ms, duty cycle $\le 50\%$	500 mA
$t_W \le 30 \text{ ns}, \text{ duty cycle} \le 0.002\% \dots$	3 A
Output clamp current, IOK	400 mA
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T <sub>A</sub>	0°C to 70°C
Storage temperature range, T <sub>stq</sub>	65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	

NOTES: 1. Voltage values are with respect to network GND.

2. Both halves of this dual circuit may conduct rated current simultaneously; however, power dissipation averaged over a short time interval must fall within the continuous power dissipation ratings.

#### **DISSIPATION RATING TABLE**

PACKAGE	$T_{\mbox{A}} \le 25^{\circ}\mbox{C}$ POWER RATING	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 70°C POWER RATING
D	725 mW	5.8 mW/°C	464 mW
Р	1000 mW	8.0 mW/°C	640 mW

# recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>	4.5	5	5.5	V
High-level input voltage, VIH	2			V
Low-level input voltage, V <sub>IL</sub>			8.0	V
Operating free-air temperature, TA	0		70	°C

# SN75476 THRU SN75478 DUAL PERIPHERAL DRIVERS

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# electrical characteristics over recommended operating free-air temperature range

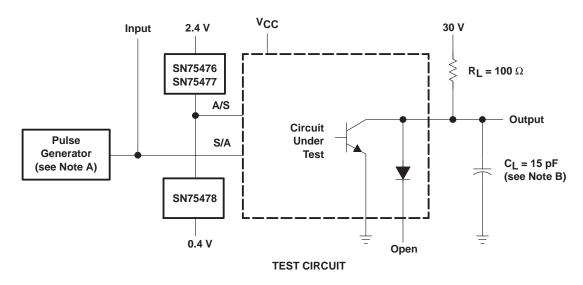
	PARAMETER		TEST C	TEST CONDITIONS			MAX	UNIT
VIK	Input clamp voltage		I <sub>I</sub> = -12 mA	$I_I = -12 \text{ mA}$			-1.5	V
			V <sub>CC</sub> = 4.5 V,	I <sub>OL</sub> = 100 mA		0.16	0.3	
VOL	Low-level output voltage		$V_{IH} = 2 V$	I <sub>OL</sub> = 175 mA		0.22	0.5	V
			V <sub>IL</sub> = 0.8 V	I <sub>OL</sub> = 300 mA		0.33	0.6	
V <sub>O(BR)</sub>	Output breakdown voltage		$V_{CC} = 4.5 \text{ V},$	I <sub>OH</sub> = 100 μA	70	100		V
V <sub>R(K)</sub>	Output clamp reverse voltage		$V_{CC} = 4.5 V,$	I <sub>R</sub> = 100 μA	70	100		V
V <sub>F(K)</sub>	Output clamp forward voltage		$V_{CC} = 4.5 V,$	I <sub>F</sub> = 300 mA	0.8	1.15	1.6	V
ЮН	High-level output current		V <sub>CC</sub> = 4.5 V, V <sub>IL</sub> = 0.8 V,	V <sub>IH</sub> = 2 V, V <sub>OH</sub> = 70 V		1	100	μΑ
lн	High-level input current		V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 5.5 V		0.01	10	μΑ
I	Low lovel input ourrent	A input		V. 0.9.V		-80	-110	
¹IL	Low-level input current	S input	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 0.8 V		-160	-220	μΑ
		SN75476		V <sub>I</sub> = 5 V		10	17	
Іссн	Supply current, outputs high	SN75477	V <sub>CC</sub> = 5.5 V	V <sub>I</sub> = 0		10	17	mA
		SN75478		V <sub>I</sub> = 5 V		10	17	
		SN75476		V <sub>I</sub> = 0		54	75	
<sup>I</sup> CCL	Supply current, outputs low	SN75477	V <sub>CC</sub> = 5.5 V	V <sub>I</sub> = 5 V		54	75	mA
		SN75478		V <sub>I</sub> = 0		54	75	

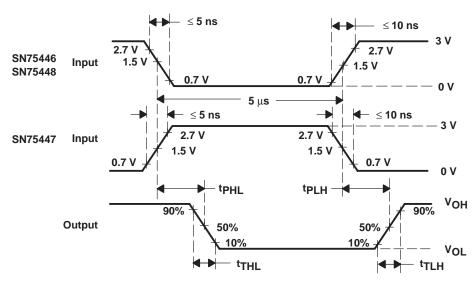
<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

# switching characteristics, $V_{CC}$ = 5 V, $T_A$ = 25°C

	PARAMETER	TEST CC	MIN	TYP	MAX	UNIT	
<sup>t</sup> PLH	Propagation delay time, low-to-high-level output				200	350	ns
t <sub>PHL</sub>	Propagation delay time, high-to-low-level output	$C_L = 15 pF,$	$R_L = 100 \Omega$ ,		200	350	ns
tTLH	Transition time, low-to-high-level output	See Figure 1			50	125	ns
tTHL	Transition time, high-to-low-level output				90	125	ns
VOH	High-level output voltage after switching	V <sub>S</sub> = 55 V, See Figure 2	$I_O \approx 300 \text{ mA},$	V <sub>S</sub> -18			mV

#### PARAMETER MEASUREMENT INFORMATION





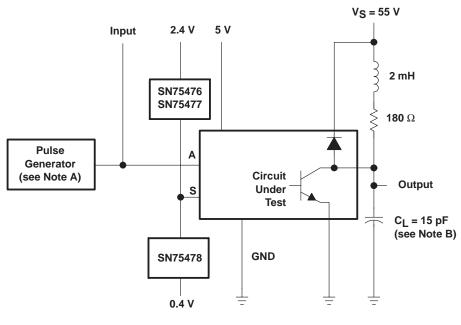
NOTES: A. The pulse generator has the following characteristics: PRR = 100 kHz,  $Z_O = 50 \Omega$ .

B. C<sub>L</sub> includes probe and jig capacitance.

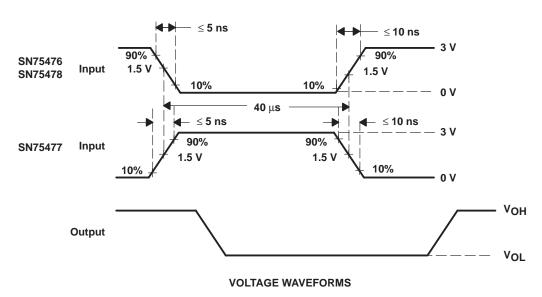
Figure 1. Test Circuit and Voltage Waveforms, Switching Characteristics

**VOLTAGE WAVEFORMS** 

### PARAMETER MEASUREMENT INFORMATION



**TEST CIRCUIT** 



NOTES: A. The pulse generator has the following characteristics: PRR = 12.5 kHz,  $Z_O = 50 \Omega$ .

B. C<sub>L</sub> includes probe and jig capacitance.

Figure 2. Latch-Up Test Circuit and Voltage Waveforms





24-Aug-2018

#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN75477D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75477	Samples
SN75477DE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75477	Samples
SN75477DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75477	Samples
SN75477DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75477	Samples
SN75477DRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75477	Samples
SN75477P	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN75477P	Samples
SN75477PE4	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN75477P	Samples
SN75478P	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN75478P	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.



## PACKAGE OPTION ADDENDUM

24-Aug-2018

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

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## TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

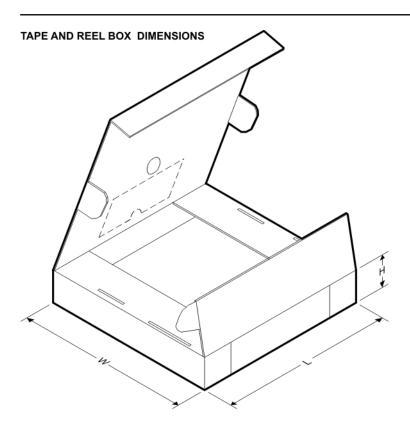
### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75477DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

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#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75477DR	SOIC	D	8	2500	340.5	338.1	20.6



SMALL OUTLINE INTEGRATED CIRCUIT



### NOTES:

- 1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
- 4. This dimension does not include interlead flash.
- 5. Reference JEDEC registration MS-012, variation AA.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



#### NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



# P (R-PDIP-T8)

# PLASTIC DUAL-IN-LINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.



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